

IN THE SPECIFICATION:

Changes for original paragraph on page 4, beginning on line 11:

After forming device 130 and any desired electronically conductive and/or insulative layers, an electrically conductive layer can be formed over substrate 110 and device 130. As an example, the electrically conductive layer can be an ohmic metal or an interconnect metal. Next, an optional insulative layer (not shown in FIG. 1) can be formed over the electrically conductive layer. Holes can be formed in the optional electrically insulative layer to expose portions 120 of the electrically conductive layer. Portions 120 of the electrically conductive layer can be electrically coupled to semiconductor device 130. In a different embodiment, the electrically conductive layer can be formed after the formation of the optional electrically insulative layer 121 as shown in the resulting structure in FIG. 1.